LN1861CTR

Surface Mounting Chip LED

GW Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Lighting Color

• Orange

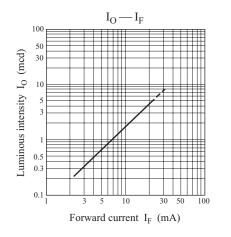
Note) *: The condition of IFP is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

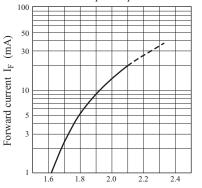
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O	$I_F = 20 \text{ mA}$	1.9	5.0		mcd
Reverse current	I _R	$V_R = 3 V$			10	μΑ
Forward voltage	V _F	$I_{\rm F} = 20 {\rm mA}$		2.1	2.8	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 20 {\rm mA}$		630		nm
Spectral half band width	Δλ	$I_{\rm F} = 20 \text{ mA}$		40		nm

I_F

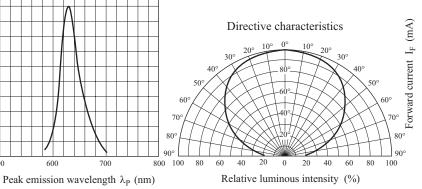
 V_{F}

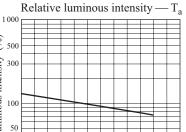


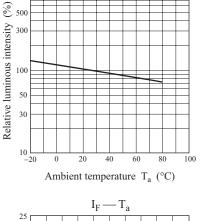
Relative luminous intensity — λ_P

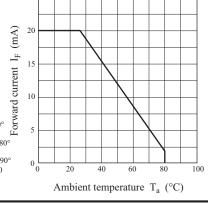












100

80

60

40

20

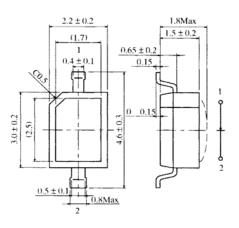
0 500

Relative luminous intensity (%)

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Package (Unit: mm)





• Pin name

1: Anode

2: Cathode

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